



Membership Application Form
会员申请表格

请将以下表格填妥后，以邮件形式提交本会办事处
Please Email your filled Application to:

深圳市福田区车公庙泰然工贸园
210栋西座8楼A37
电话: +86-21-56093010
邮箱:peggychen@smta.org.cn

Suite A37, 8/F, Block West, Bldg 210,
Chekung Miao Ind. Area, Futian District, Shenzhen 518040, PRC
Tel: +86-21-56093010
Email: peggychen@smta.org.cn

(一)Section A: 会员分类Membership Category

请选择加入的会员类别 (每年) Please select the Membership Category (Per Year)

- 企业会员Corporate Membership 人民币5700 / ¥5700
- 个人会员Individual Membership 人民币900 / ¥900
- 学生会会员Student Members hip 人民币50 / ¥50

(二)Section B: 申请者个人资料Member Information

姓名Name:教授 Prof/博士Dr/先生Mr/女士Mrs/小姐Ms _____
 职业Job Title _____
 联系地址Mailing Address: _____
 联络电话Contact Number: (手机) Mobile: _____ (公司) Company: _____
 电邮Email Address: _____

所属工作岗位Please check your primary job function

- 线路设计Circuit Design/包装设计Package Design
- 制造Production Manufacturing/生产加工Process Engineering
- 品质控制Quality Control/ Quality Assurance
- 研究及开发Research & Development
- 工程支援Engineering Support
- 其他Other: _____
- 采购Purchasing/Procurement
- 销售Sales and Marketing
- 顾问Consulting
- 学生/学术界Student/Academic
- 管理层Managerial

公司名称Company Name: _____
 公司简介Company Description: _____
 公司网站Company URL: _____

公司现有员工数目Number of employees at your company

- 1-50
- 51-100
- 101-250
- 250-

公司之产品及服务的最终对象为Primary end product manufactured / service performed

- 零零售用Consumer
- 工业用Industrial
- 军事用Military
- 汽车用Automotive
- 医学用Medical
- 航空及航海用Aviation / Aerospace
- 通讯用Communications
- 电脑设备Computing Equipment
- 合约生产Contract Manufacturing
- 半导体、集成电路、混合线路Semiconductors, ICs, Hybrid Circuit
- 测试Test& Reliability
- 其他Others

会员性质Membership Nature

- 本公司对于表面装贴设备及材料是使用者My company is a USER of Surface Mount Equipment and Materials (Includes contract manufactures and consultants)
- 本公司对于表面装贴设备及材料是供应者My Company is a SUPPLIER of Surface Mount Equipment and Materials

(三) Section C: 缴交会费Payment Type

请以邮件方式提交会员登记表格，收到付款通知书后请到银行付款

Please submit the membership application form by email and make the payment to the bank account upon receipt of invoice

申请人签署Applicant Signature _____ 日期Date _____